



Fellow, Honggun Kim

(TEL, Korea)



Honggun Kim led project management to collaborate within the group, multiple groups, and suppliers. Delivered critical issue resolution skill in unit process development and integration-related problems for CVD and ALD of all devices (DRAM, Flash, Logic) at Samsung Electronics. He participated Cu/low-k Interconnect program as Samsung assignee at IMEC (International Microelectronics Centre) consortium in Belgium. He organized and led cross-functional teams to address issues and delivered solutions to customers. Participated in the development of product or business strategy, drove Successful engagements for new products at Applied Materials. Led the development for advanced module engagement. Currently, he drives future semiconductor development strategy and technology mid to long-term and pathfinder for new opportunities at TEL.

Work Experience

1999.1 ~ 2017.5: Samsung Electronics R&D center, Principal Eng'r (South Korea)

- Thin Film Process development for Memory and Logic
- Device TFT for DRAM, NAND, and Logic
- Samsung assignee for BEOL Cu/low-k at Belgium IMEC

2017.6 ~ 2021.12: Applied Materials, Director (US)

- Plasma Process development for Memory and Logic
- Business strategy & Customer engagement

2022.1 ~ Current: TEL Korea, Fellow (South Korea)

- Thin Film New products strategy & Roadmap for future generations
- Module collaboration with Dep/Etch/Removal